

SR-SMD 4.50/05/90LF 1.5AU BK BX

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26 D-32758 Detmold Germany

www.weidmueller.com













The integrated rail bus for the modular electronics housing system

When supplying, connecting or distributing within modular applications, the rail bus can replace the tedious individual wiring process with a flexible and uninterrupted system-wide solution.

The system bus is securely integrated within the 35-mm standard mounting rail. The SMD-bus contact block can be reflow-soldered so that it can be completely automatically processed during the component assembly. The resistant, gold-plated contact surfaces ensure a permanent and reliable contact for all housing widths.

- **Unlimited scalability** The integrated connection solution covers all system widths: from the 6-mm slice to the 67-mm large-area housing.
- Easy to service during installation It's easy to replace a module, even in existing modules groups without any influence on the neighbouring modules.
- **Universal integration** The uninterrupted system bus is securely integrated within the 35-mm standard mounting rail.
- Maximum availability Five fully-galvanized and partially gold-plated twin-arched contacts are used to establish a permanent contact to the rail bus. THR solder flanges ensure that the connection to the circuit board is stable.

General ordering data

Version	PCB plug-in connector, Bus-contact block for CH20M12-67, Solder flange, THT/THR solder connection, Number of poles: 5, 180°, Solder pin length (I): 1.5 mm, Gold-plated, black
Order No.	<u>1155890000</u>
Туре	SR-SMD 4.50/05/90LF 1.5AU BK BX
GTIN (EAN)	4032248942527
Qty.	78 pc(s).
Product data	UL:
Packaging	Вох



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Technical data

Dimensions and weights

Height	5.9 mm	Height (inches)	0.232 inch
Length	24 mm	Length (inches)	0.945 inch
Net weight	3.05 g	Width	16.3 mm
Width (inches)	0.642 inch		

Material data

Insulating material	LCP	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	Illa
Comparative Tracking Index (CTI)	≥ 175	Insulation strength	≥ 10 ⁸ Ω
Moisture Level (MSL)	1	Contact surface	Gold-plated
Storage temperature, min.	-40 °C	Storage temperature, max.	70 °C
Operating temperature, min.	-50 °C	Operating temperature, max.	100 °C
Temperature range, installation, min.	-30 °C	Temperature range, installation, max.	100 °C

Rated data acc. to IEC

General data

Colour	black	Colour chart (similar)	RAL 9011	
Protection degree	IP20			

Material data

Comparative Tracking Index (CTI)	≥ 175	Insulating material	LCP
Insulating material group	Illa		

Classifications

ETIM 6.0	EC001031	ETIM 7.0	EC001031
ECLASS 9.0	27-18-27-90	ECLASS 9.1	27-18-27-90
ECLASS 10.0	27-18-27-92	ECLASS 11.0	27-18-27-92

Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized		
	standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties		
	in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.		

Approvals

c SN us III	
Conform	
E60693	
	C S US LILL

Downloads

Engineering Data	STEP	
Engineering Data	<u>EPLAN</u>	



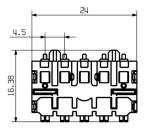
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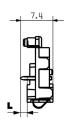
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Drawings

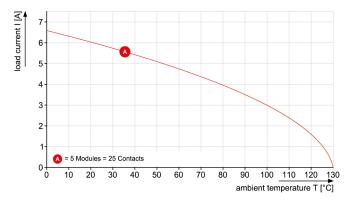












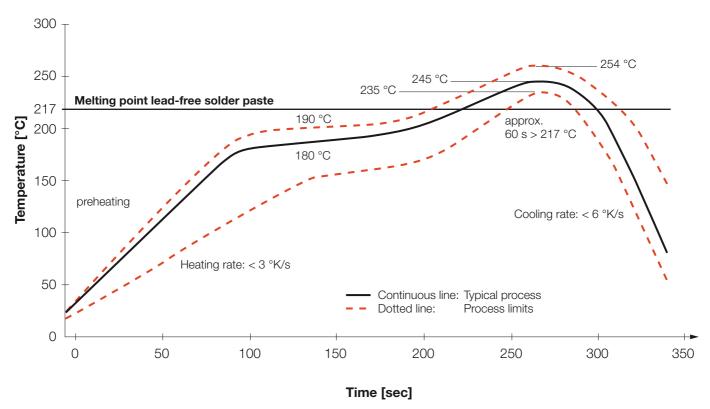


Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- · Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.